## Part Numbering

Chip Coils (SMD)

(Part Number)

L	Q	Н	32	м	Ν	331	κ	2	3	L
	D	2	8	4	6	6	0	8	9	0

Product ID

Product ID	
LQ	Chip Coils

#### 2 Structure

Code	Structure				
G	Monolithic Type (Air-core Coil)				
н	Winding Type (Ferrite Core)				
м	Monolithic (Ferrite Core)				
Р	Film Type				
w	Winding Type (Air-core Coil)				

#### 3 Dimensions (LXW)

Code	Dimensions (L×W)	EIA
03	0.6×0.3mm	0201
15	1.0×0.5mm	0402
18	1.6×0.8mm	0603
21	2.0×1.25mm	0805
2B	2.0×1.5mm	0805
31	3.2×1.6mm	1206
32	3.2×2.5mm	1210
3K	3.3×3.3mm	1212
43	4.5×3.2mm	1812
55	5.7×5.0mm	2220
66	6.3×6.3mm	2525

#### Applications and Characteristics

Code	Series	Applications and Characteristics		
н	LQG	Monolithic Air-core		
N		for Resonant Circuit		
D	LQM	for Choke (Low-current DC Power Supplies)		
F		for Choke (DC Power Supplies)		
м	LQP	Film Type		
т	LQF	Film Type (Low DC Resistance Type)		
Α	LQW	High Q Type (UHF-SHF)		
н	LQW	High Q Type (VHF-UHF)		
N		for Resonant Circuit		
м		for Resonant Circuit (Coating Type)		
D	LQH	for Choke		
С	LQN	for Choke (Coating Type)		
S		for Choke (Magnetically Shielded Type)		
Н		for High-frequency Resonant Circuit		

#### **5**Category

Code	Category
N	Standard Tupa
S	Standard Type

#### 6Inductance

Expressed by three figures. The unit is micro-henry ( $\mu$ H). The first and second figures are significant digits, and the third figure expresses the number of zeros which follow the two figures. If there is a decimal point, it is expressed by the capital letter "**R**". In this case, all figures are significant digits. If inductance is less than 0.1 $\mu$ H, the inductance code is expressed by a combination of two figures and the capital letter "**N**", and the unit of inductance is nano-henry (nH).

The capital letter " $\mathbf{N}$ " indicates the unit of "nH", and also expresses a decimal point. In this case, all figures are significant digits.

Inductance Tolerance

Code	Inductance Tolerance
В	±0.1nH
С	±0.2nH
D	±0.5nH
G	±2%
Н	±3%
J	±5%
к	±10%
М	±20%
N	±30%
S	±0.3nH
w	±0.05nH

#### 8Features

Code	Features	Series
0	Standard Type	LQG/LQP/LQW/LQM*1/LQH*2
	High-Q/ Low DC Resistance	LQW15A/LQW18A/LQW2BH
1	Standard Type	LQM21N
	Low DC Resistance	LQH32C
2	Standard Type	LQH32C/LQH32M/LQH3KS
3	Low DC Resistance	LQH32C
5	Low Profile Type	LQH32C/LQH3KS

\*1 : Except LQM21N series

\*2 : Except LQH32/LQH3K series

# electrode

•Lead (Pb) Free

Code	Electrode	Series		
0	Sn	LQG18H/LQP03T/LQW□□A/LQM		
2	511	LQG15H/LQP (Except LQP03T)		
3	LF Solder	LQW H/LQH		

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(Part Number)



Packaging

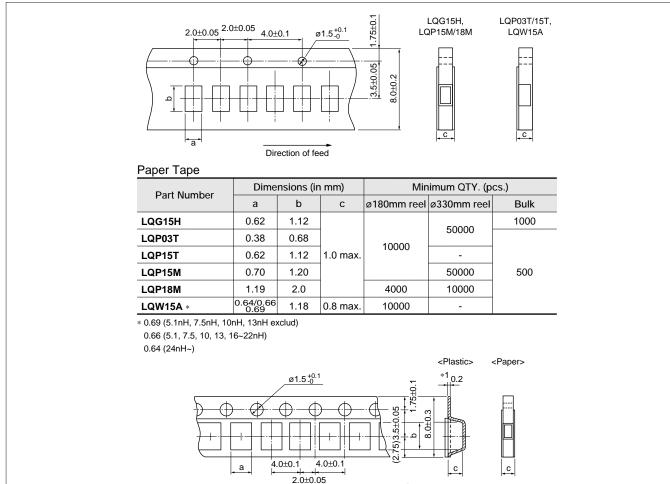
Code	Packaging	Series
к	Plastic Taping (ø330mm Reel)	LQH*1 /LQW   H/LQM31F/LQM21*2
L	Plastic Taping (ø180mm Reel)	LQH/LQWDH/LQM31F/LQM21*2
В	Bulk	All series
J	Paper Taping (ø330mm Reel)	LQW18A/LQG/LQM18N/LQM21*3 /LQP*4
D	Paper Taping (ø180mm Reel)	LQW_A/LQG/LQM18N/LQM21*3 /LQP

\*1 Except LQH43C/LQH66S

\*2 LQM21D(22 - 47μH)/LQM21F(4.7 - 47μH)/LQM21N(2.7 - 4.7μH) only. \*3 LQM21D(1.0 - 10μH)/LQM21F(1.0 - 2.2μH)/LQM21N(0.1 - 2.2μH) only. \*4 Except LQP15T



# ■ Minimum Quantity and 8mm Width Taping Dimension





## Paper Tape

Part Number	Dimensions (in mm)			Minimum QTY. (pcs.)		
Fait Number	а	b	с	ø180mm reel	ø330mm reel	Bulk
<b>LQM21N</b> (0.1-2.2µH)	1.45	2.25	- 1.1 max.	4000	10000	1000
<b>LQM21D</b> (1-10μH)						
<b>LQM21F</b> (1-2.2µH)						
LQG18H	4.05	1.85				
LQM18N	1.05					
LQW18A_00	1.0	1.8				500
LQW18A_10	1.1	1.9				500

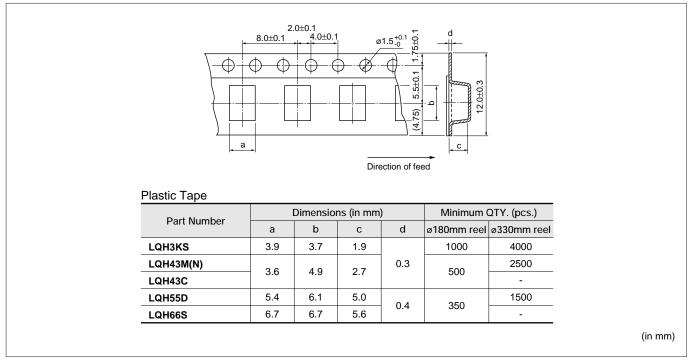
### Plastic Tape

Part Number	Dimensions (in mm)			Minimum QTY. (pcs.)		
Fait Number	а	b	с	ø180mm reel	ø330mm reel	Bulk
<b>LQM21N</b> (2.7-4.7µH)						
<b>LQM21D</b> (22-47µH)	1.45	2.25	1.3	3000	10000	1000
<b>LQM21F</b> (4.7-47µH)						
LQM31F	1.9	3.5	1.3			
LQH31M/31C/31H, LQW31H	1.9	3.6	2.0			
LQW2BH	1.75	2.3	2.0	2000	7500	
LQH32M, LQH32C_33/_23	2.9	0.0	2.1		7500	-
LQH32C_53	2.9	3.6	1.7			

(in mm)



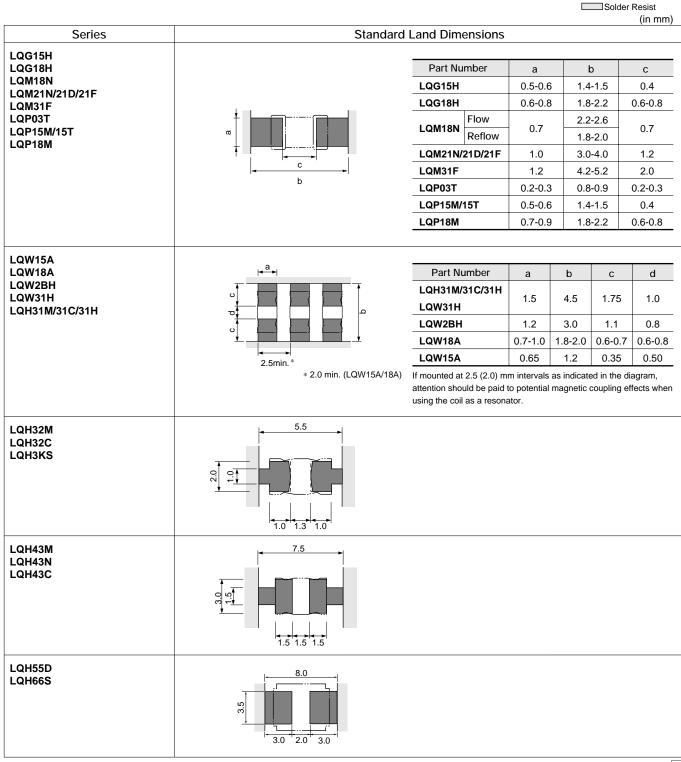
# Minimum Quantity and 12mm Width Plastic Taping Dimension





## 1. Standard Land Dimensions

A high Q value is achieved when the PCB electrode land pattern is designed so that it does not project beyond the chip coil electrode.

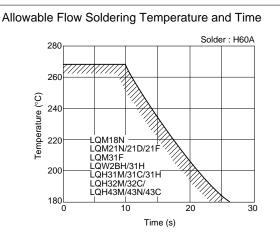


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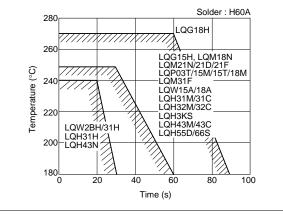
Land Pattern



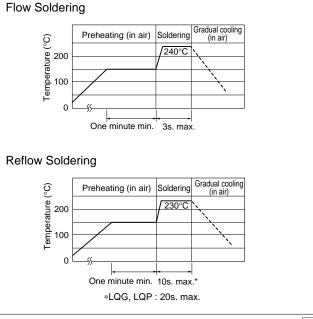
- 2. Standard Soldering Conditions
- (1) Soldering method
  Chip coils can be flow or reflow soldered.
  Please contact Murata regarding other soldering methods.
  As for LQG, LQP, LQW15A/18A, LQH3KS/55D/66S series, please use reflow soldering.
- (2) Soldering Temperature and Time Solder within the temperature and time combinations indicated by the slanted lines in the following graphs. If soldering is repeated, please note that the allowed time is the accumulated time.
- Solder : Use H60A, H63A(JIS Z 3282) or equivalent. Use solder paste equivalent to H60A for LQP03T/15M/15T/18M and LQG15H/18H.
- Flux : Use rosin-based flux, but not strongly acidic flux (with chlorine content exceeding 0.2wt%). Do not use water-soluble flux.



# Allowable Reflow Soldering Temperature and Time



# (3) Standard Soldering Conditions



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(4) Reworking with Soldering Iron

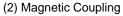
Preheating at 150°C for 1 minute is required. Do not directly touch the ceramic element with the tip of the soldering iron. The reworking soldering conditions are as follows:

Soldering iron power output : 30W max. Temperature of soldering iron tip : 280°C Diameter of soldering iron end : 3.0mm max. Soldering time : within 3 s

## 3. Mounting Instructions

#### (1) Land Pattern Dimensions

Large lands reduce Q of the mounted chip. Also, large protruding land areas (bordered by lines having dimensions 'c' and 'd' shown below) cause floating and electrode leaching.



Since some chip coils are constructed like an open magnetic circuit, narrow spacing between coils may cause magnetic coupling.

The LQG and LQM LQH3KS/66S series have a magnetically shielded structure. The structure makes their coupling coefficient smaller than that of conventional chip coils.

## (3) PCB Warping

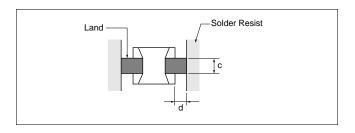
PCB should be designed so that products are not subjected to the mechanical stress caused by warping the board.

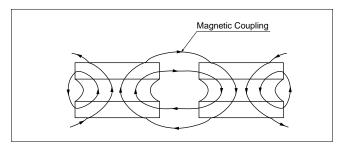
Products should be located in the sideways direction (Length:a<b) to the mechanical stress.

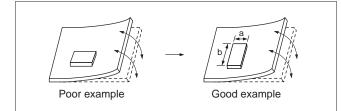
(4) Amount of Solder Paste

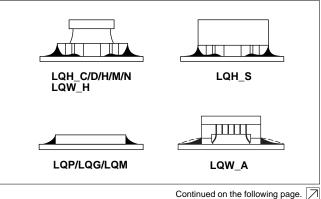
Excessive solder causes electrode corrosion, while insufficient solder causes low electrode bonding strength. Adjust the amount of solder paste so that solder is applied as shown on the right.

 Standard thickness of solder paste LQP/LQG/LQM/LQW\_A: 100 to 150µm LQH/LQW\_H : 200 to 300µm





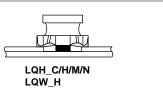






## (5) Amount of Adhesive

If too much adhesive is applied, then it may overflow into the land or termination areas and yield poor solderability. In contrast, if insufficient adhesive is applied, or if the adhesive is not sufficiently hardened, then the chip may become detached during flow soldering. Apply the adhesive in accordance with the following conditions:





LQP/LQG/LQM

Part Number	Typical Application Amount (in:mg)		
	MR-8153RA	NF-3000	
LQM18N	0.05-0.06	0.06-0.07	
LQM21N/21D/21F	0.15-0.20	0.20025	
LQM31F	0.20-0.25	0.25-0.30	
LQW2BH	0.116-0.18	-	
LQH31M/31C/31H	0.48.0.20	0.20-0.25	
LQW31H	0.18-0.20		
LQH32M/32C	0.20-0.23	0.27-0.35	
LQH43M(N)	0.45.0.50	0.60-0.80	
LQH43C	0.45-0.50		

### 4. Cleaning

The following conditions should be observed when cleaning chip coils:

- (1) Cleaning Temperature : 60°C max. (40°C max. for alcohol cleaning agents)
- (2) Ultrasonic

Output : 20W/I max.

Duration : 5 minutes max.

Frequency : 28 to 40kHz

Care should be taken not to cause resonance of the PCB and mounted products.

(3) Cleaning agent

The following cleaning agents have been tested on individual components. Evaluation in complete assembly should be done prior to production.

a) Alcohol cleaning agents Isopropyl alcohol (IPA)

- b) Aqueous cleaning agents
  - Surface active agent (Clean Thru 750H \*1)
  - High grade alcohol (Pine Alpha ST-100S \*1)
  - Hydrocarbon (Techno Cleaner 375)
  - Alkaline Saponifier (Aqua Cleaner 210SEI \*2)

LQH, LQH\_S series : Aqueous agents should not be used because they may cause quality deterioration.

- \*1 LQH series : Surface active agent and high grade alcohol can be used.
- \*2 cleaner should be diluted to 15% using deionized water.
- (4) Ensure that flux residue is completely removed.
   Component should be thoroughly dried after aqueous agents have been removed with deionized water.
   For additional cleaning methods, please contact Murata.



# **Chip Coils Recommended conversion table**

ex.

Winding Type for High-frequency Part Number LQH31HN54NK<u>01</u>K Recommended Part Number LQH31HN54NK<u>03</u>K

Туре	P/N		Recommended P/N
Film Type for High-frequency	LQP18M	00	LQP18M 02
Winding Type for High-frequency	LQW2BH	01	LQW2BH 03
	LQW2BH	11	LQW2BH 13
	LQW31H	01	LQW31H 03
	LQH31H	01	LQH31H 03
Winding Type for General use	LQH31M	01	LQH31M 03
	LQH32M	21	LQH32M 23
	LQH43M	01	LQH43M 03
	LQH43N	01	LQH43N 03
Winding Type for Choke	LQH31C	01	LQH31C 03
	LQH32C	11	LQH32C 33
	LQH32C	21	LQH32C 23
	LQH32C	51	LQH32C 53
	LQH43C	01	LQH43C 03
Magnetic Shielded Type For Choke	LQH3KS	21	LQH3KS 23
Winding Type for Choke	LQH55D	01	LQH55D 03
Magnetic Shielded Type For Choke and Large Current	LQH66S	01	LQH66S 03

